IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: James C Matayabas et al.

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Docket No.: 884.946US1	Serial No.: 10/612,328
Filed: June 30, 2003	Due Date: April 30, 2005
Examiner: Howard Weiss	Group Art Unit: 2814

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X A return postcard.
X An Amendment and Response under 37 CFR 1.116 (6 Pages).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
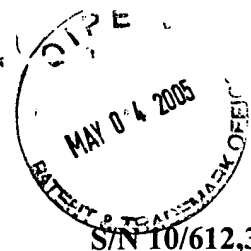Customer Number 21186

By: _____
Atty: Janal M. Kalis
Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this _29th_ day of April, 2005.

_____Amy Moriarty_____
Name

_____
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
<div align="center">(GENERAL)</div>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	James C Matayabas et al.	Examiner:	Howard Weiss
Serial No.:	10/612,328	Group Art Unit:	2814
Filed:	June 30, 2003	Docket No.:	884.946US1
Title:	POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION		
Assignee:	Intel Corporation	Customer No.:	21186

AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Final Office Action mailed <u>March 30, 2005</u>, please amend the application as follows: